

FIG. 1

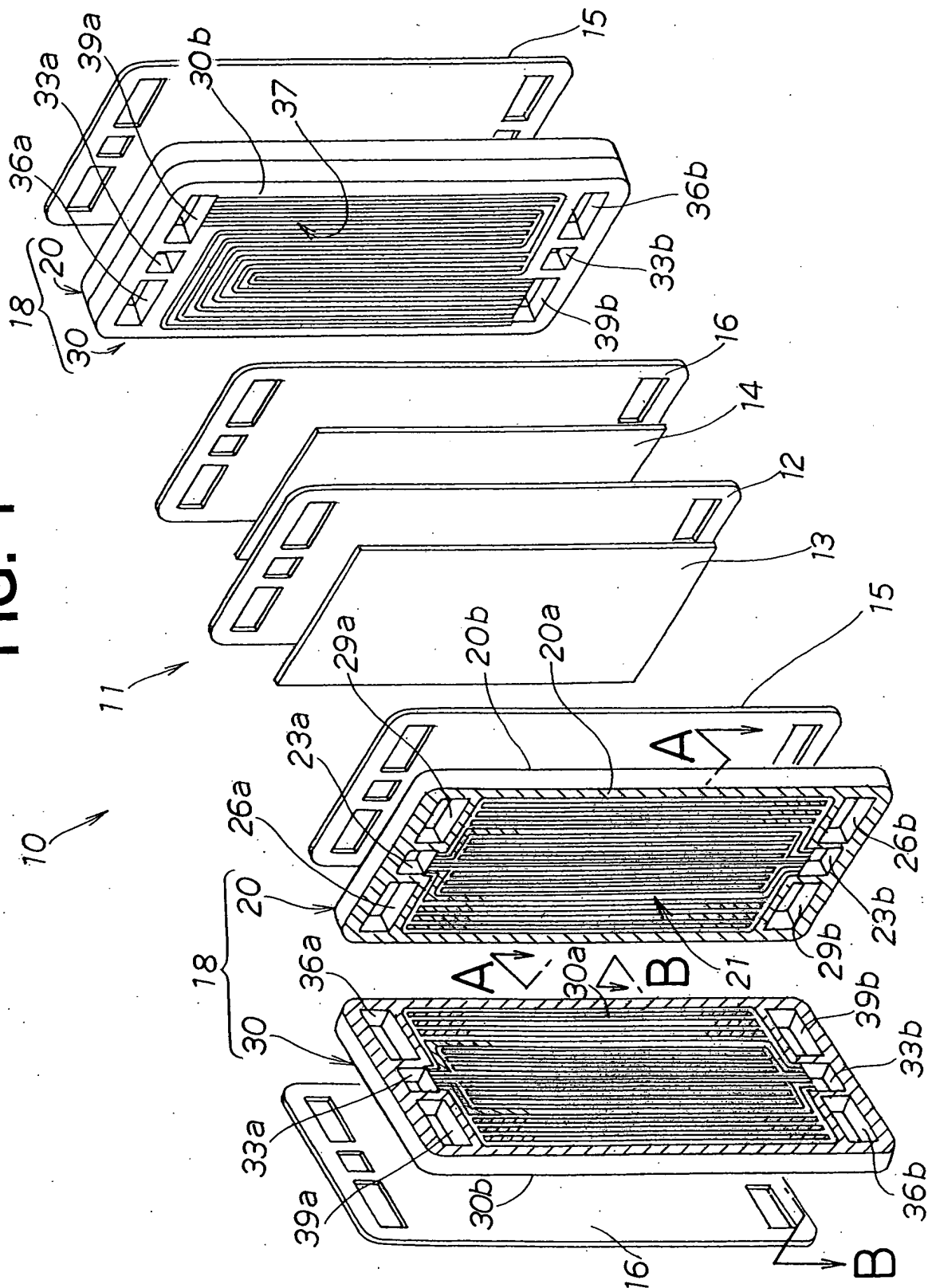


FIG. 2

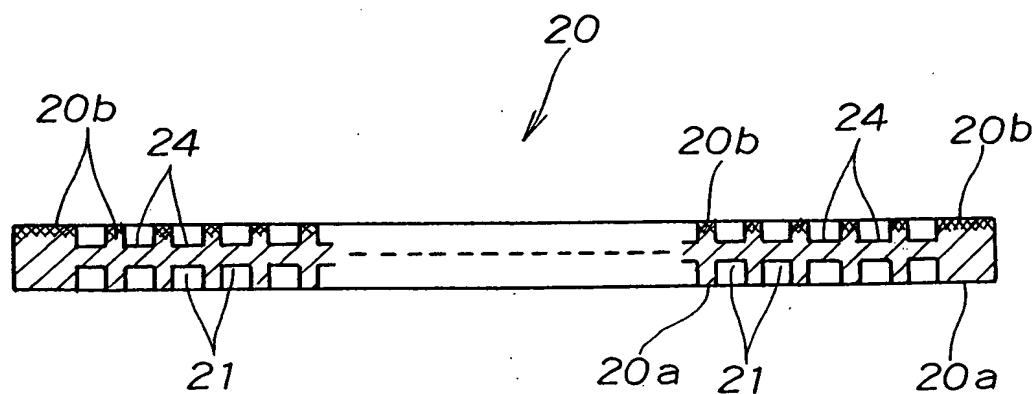


FIG. 3

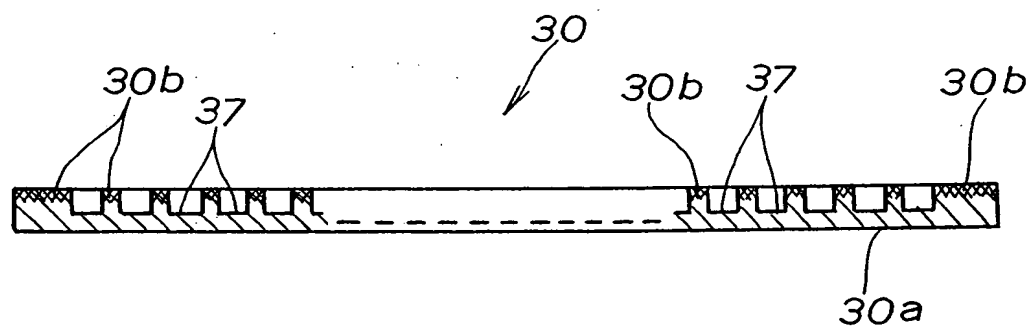


FIG. 4

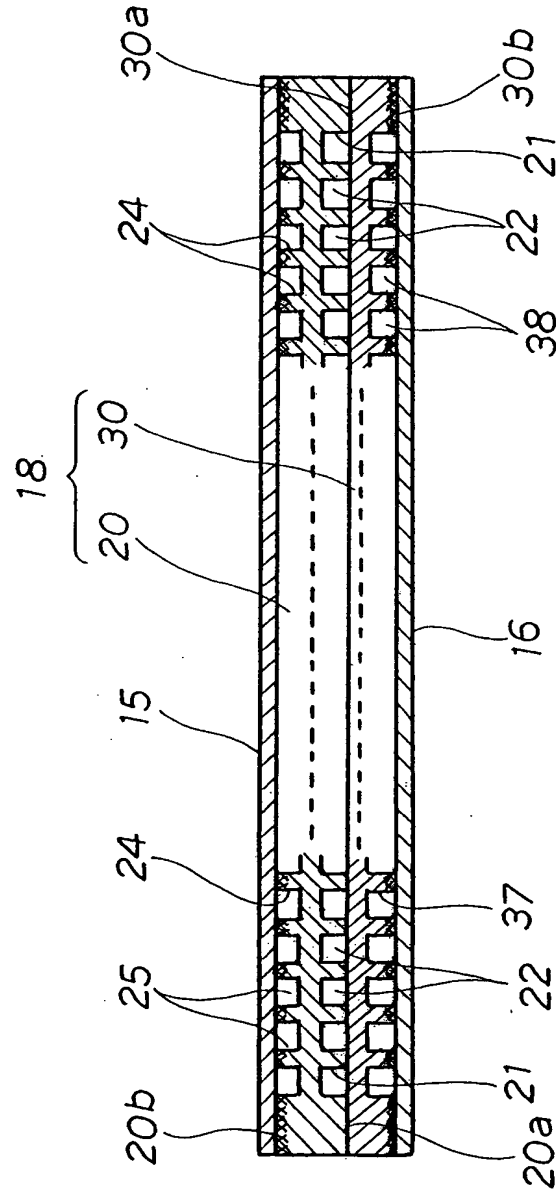


FIG. 5

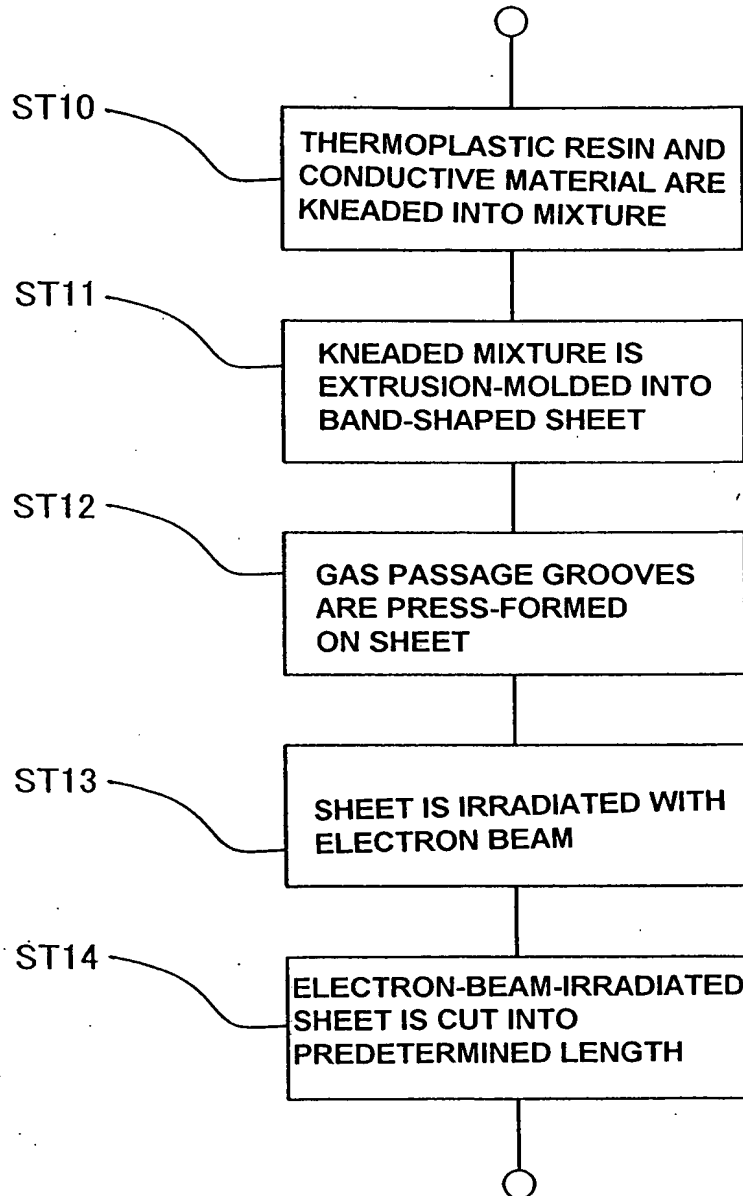


FIG. 6A

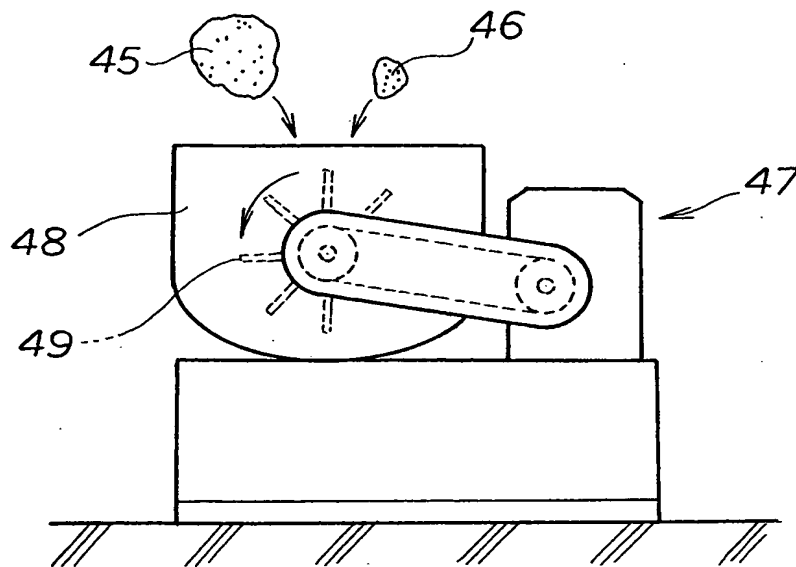


FIG. 6B

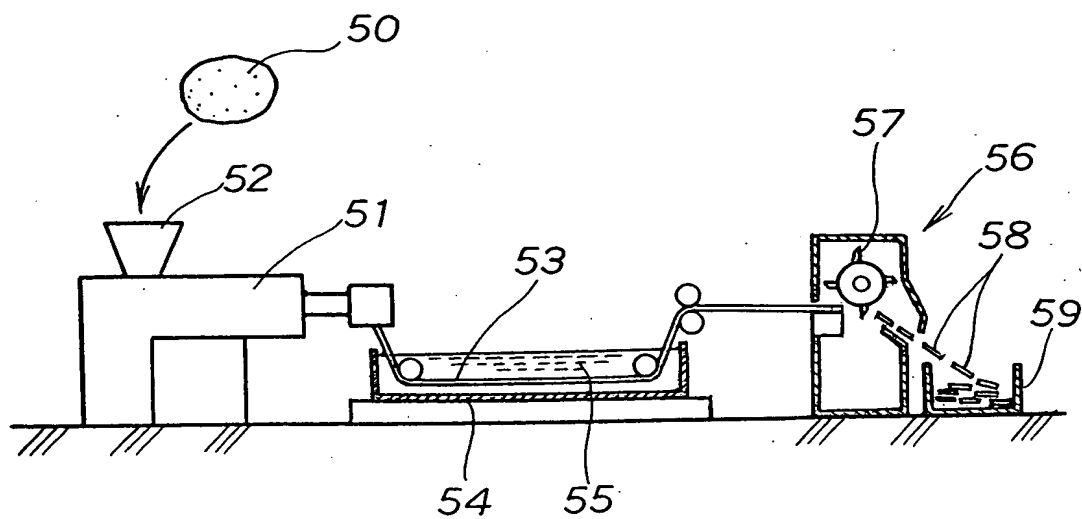


FIG. 7

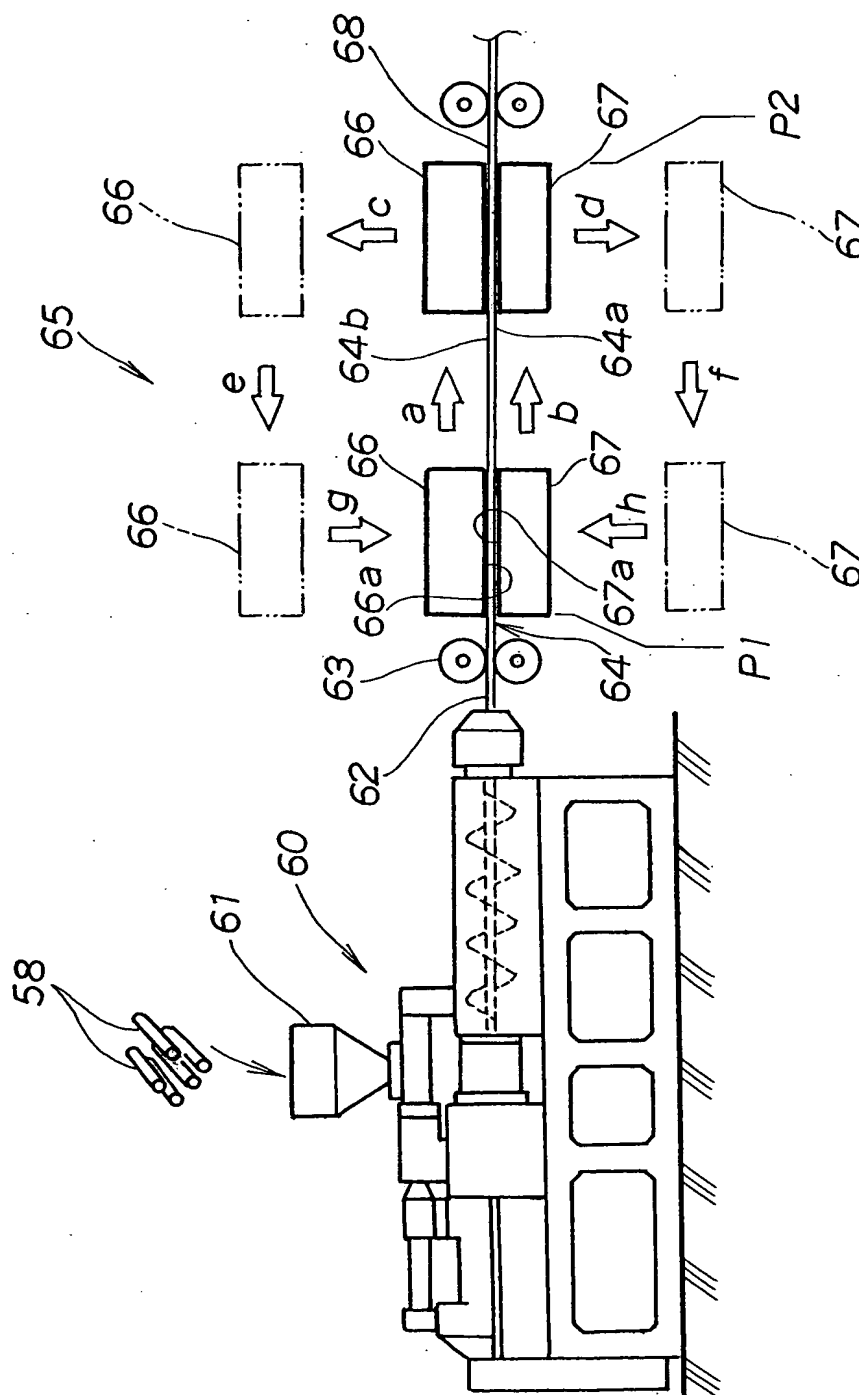
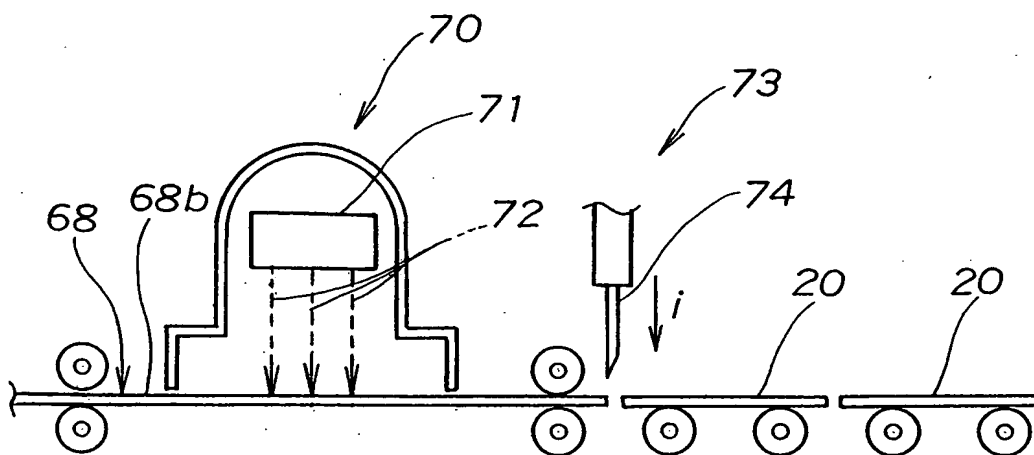


FIG. 8



10/517 017

FIG. 9

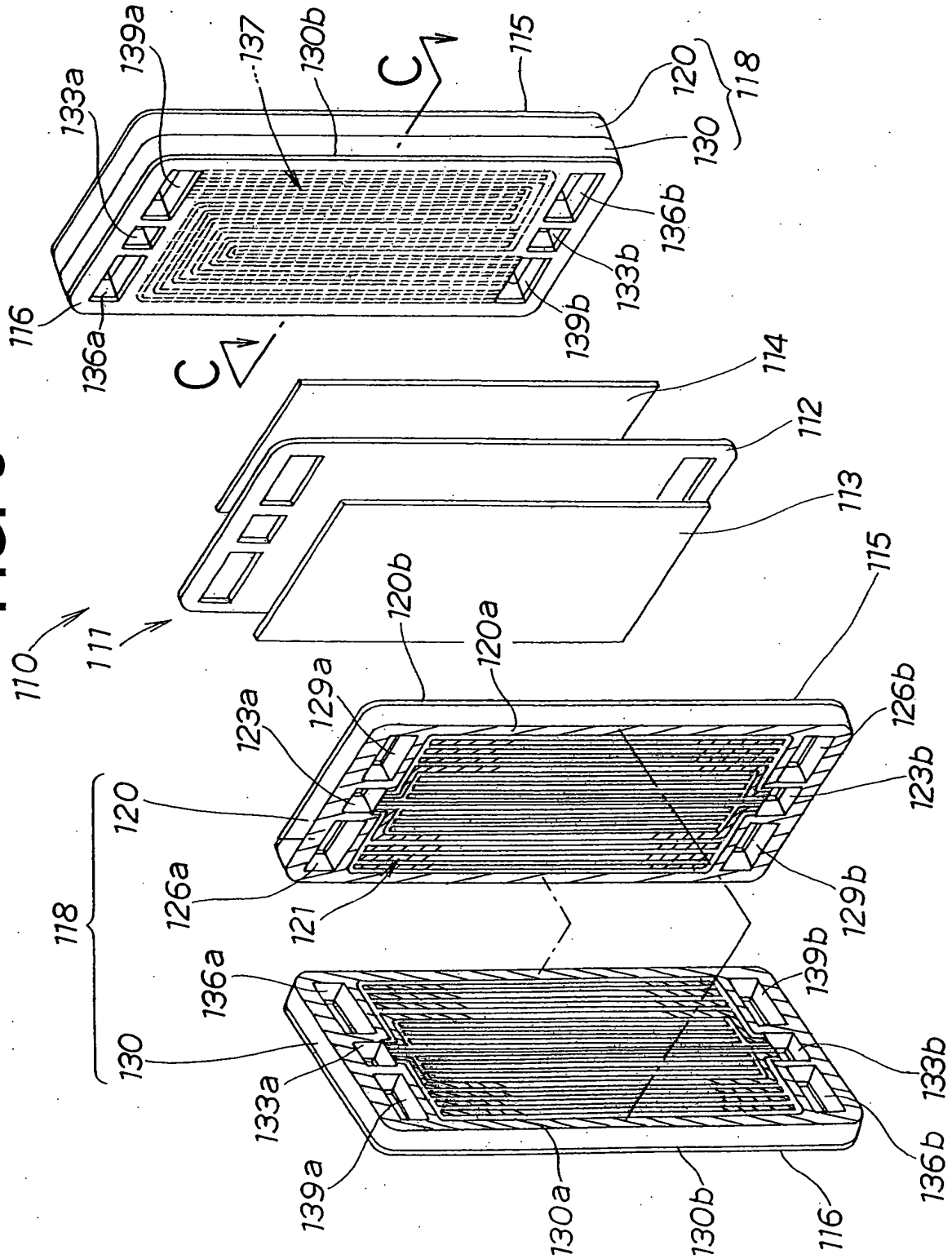
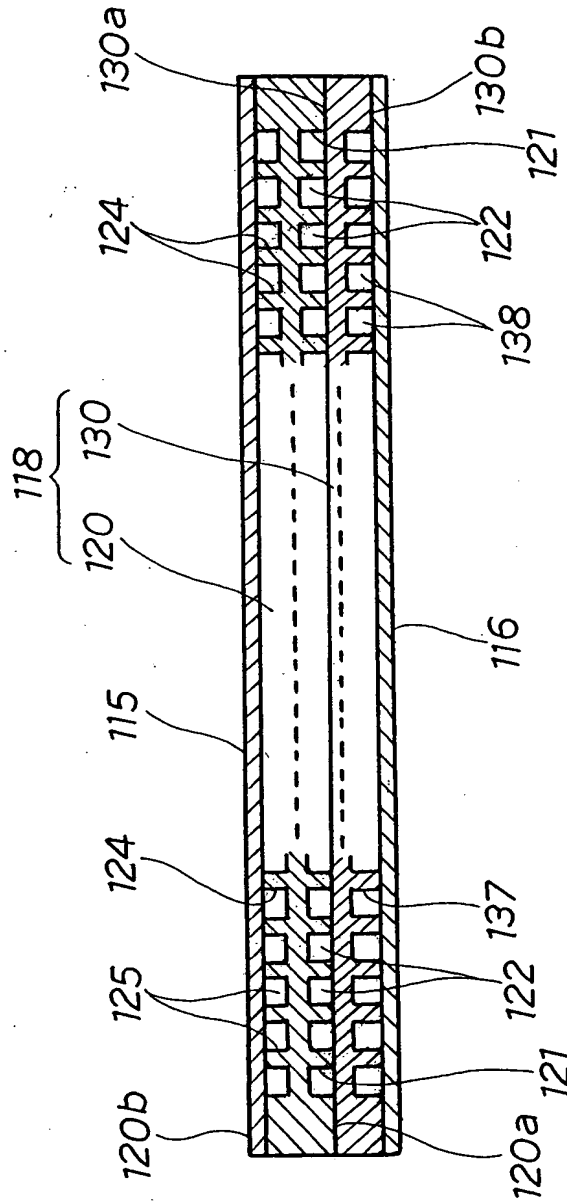


FIG. 10



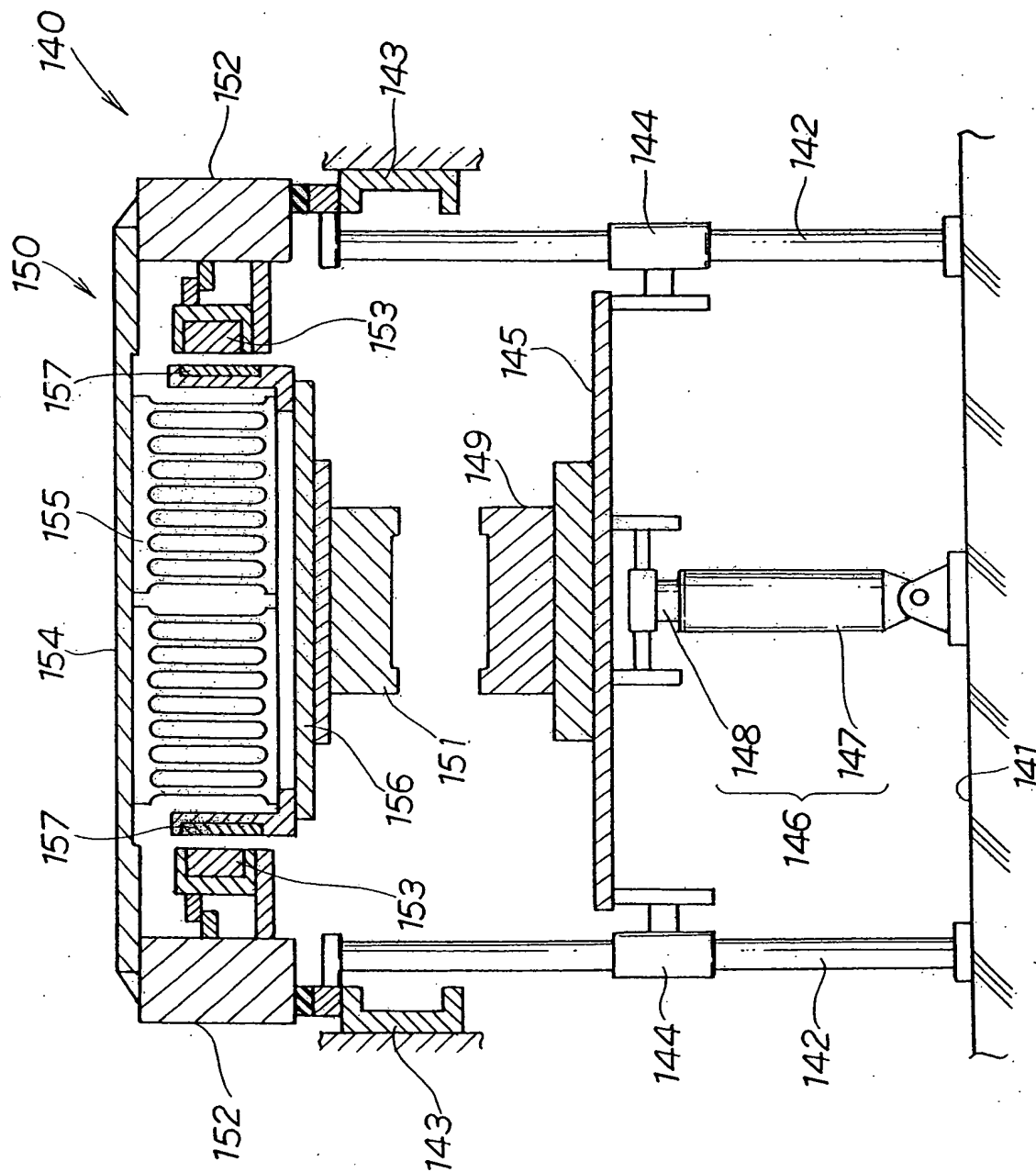


FIG. 12A

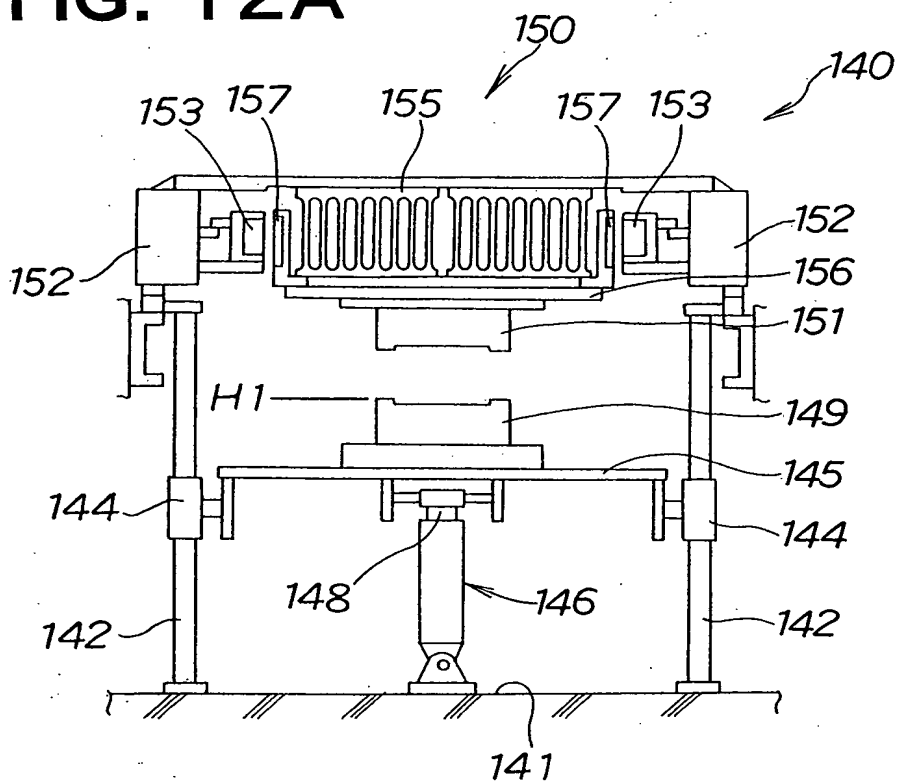


FIG. 12B

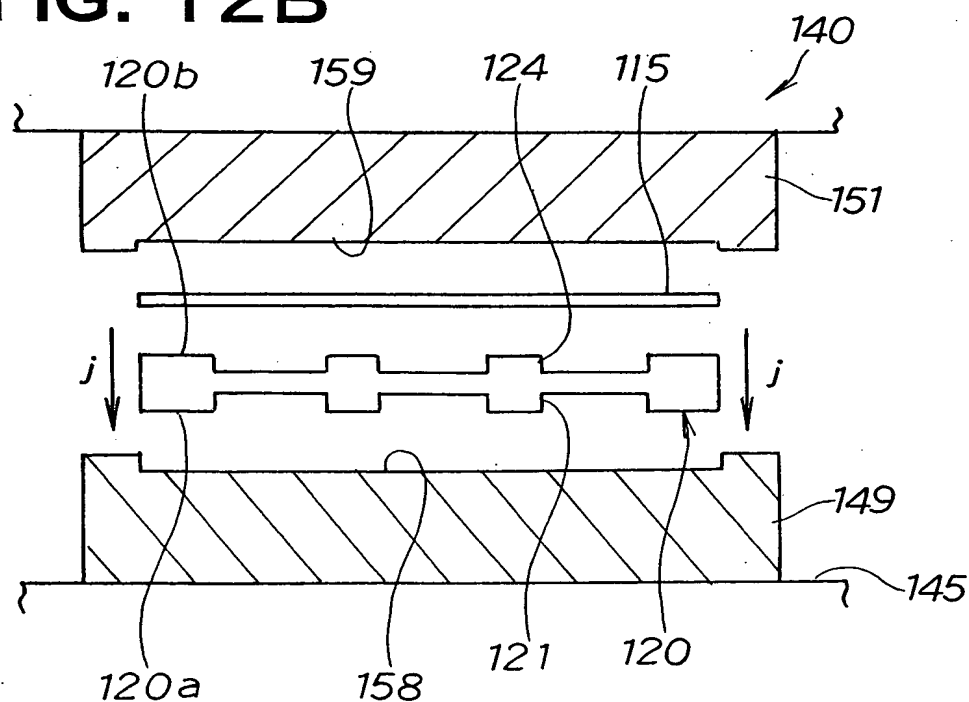


FIG. 1 3A

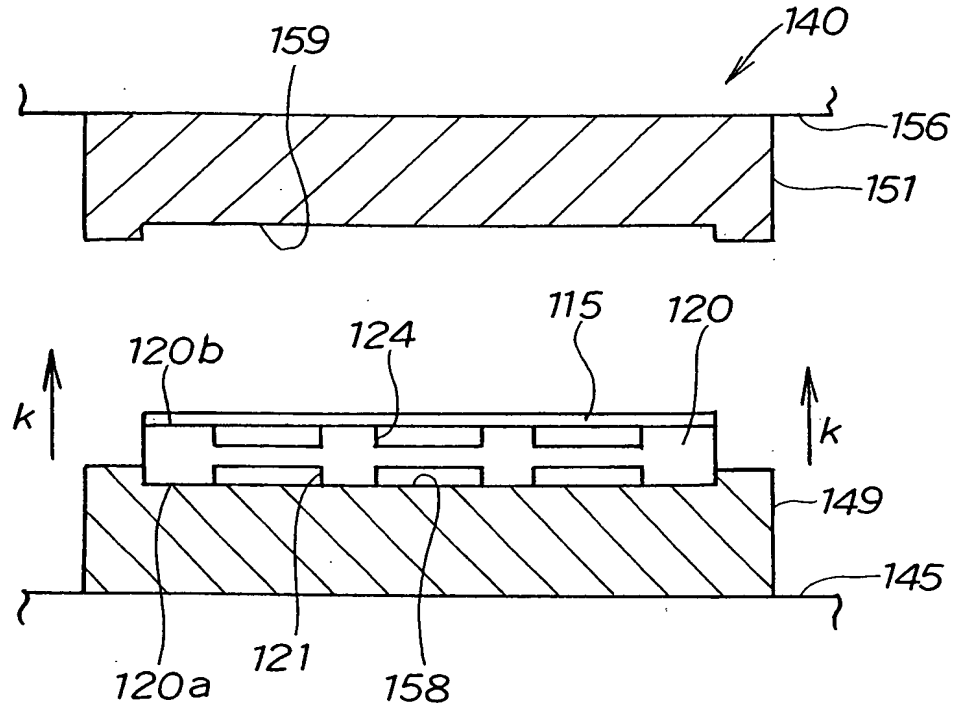


FIG. 1 3B

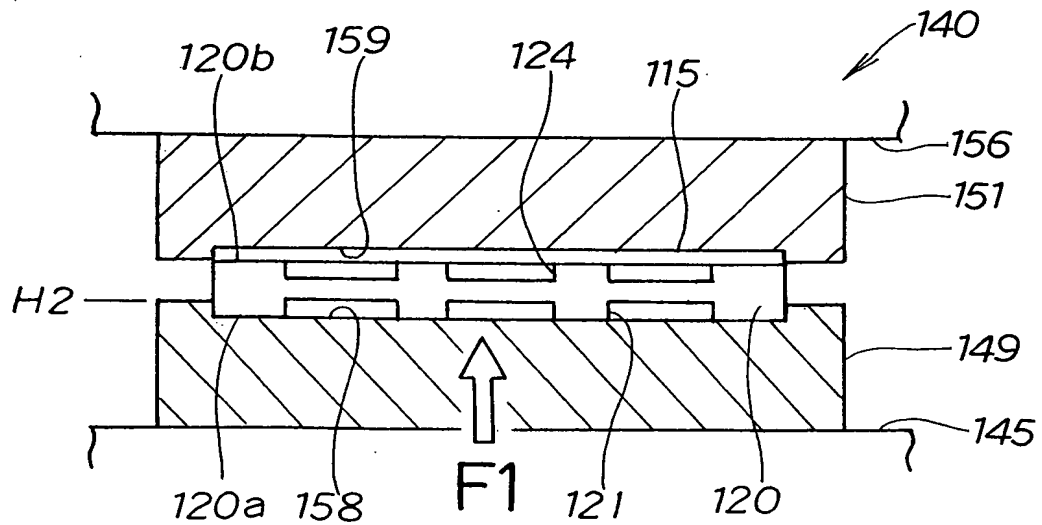


FIG. 1 4A

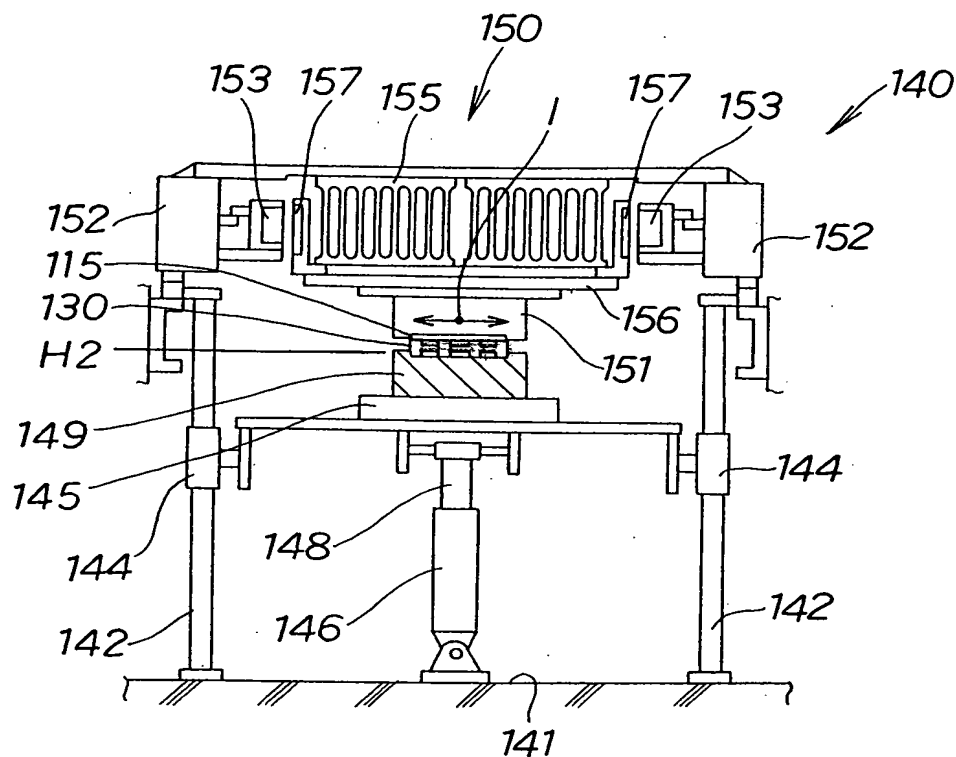


FIG. 1 4B

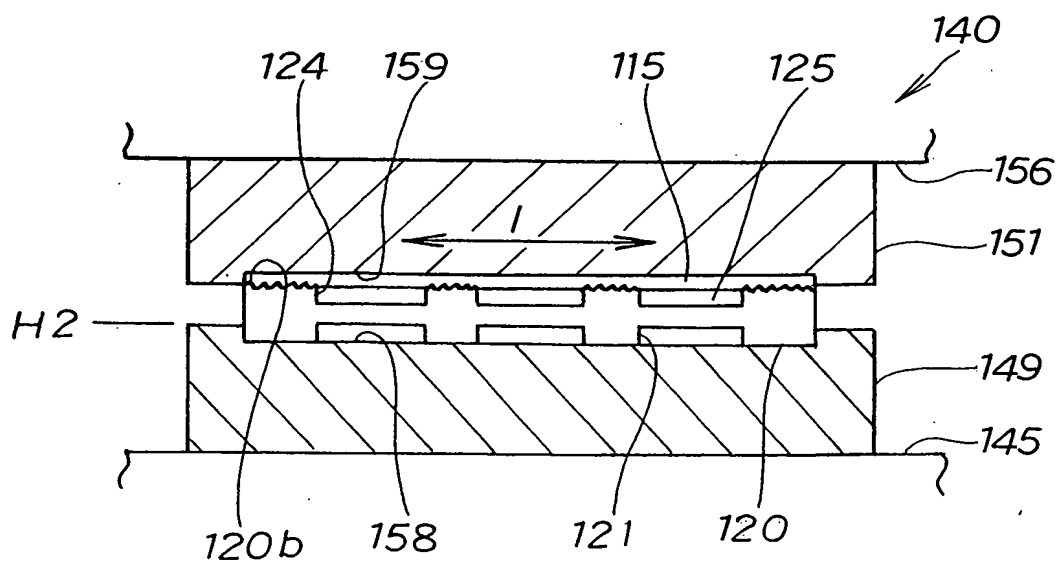
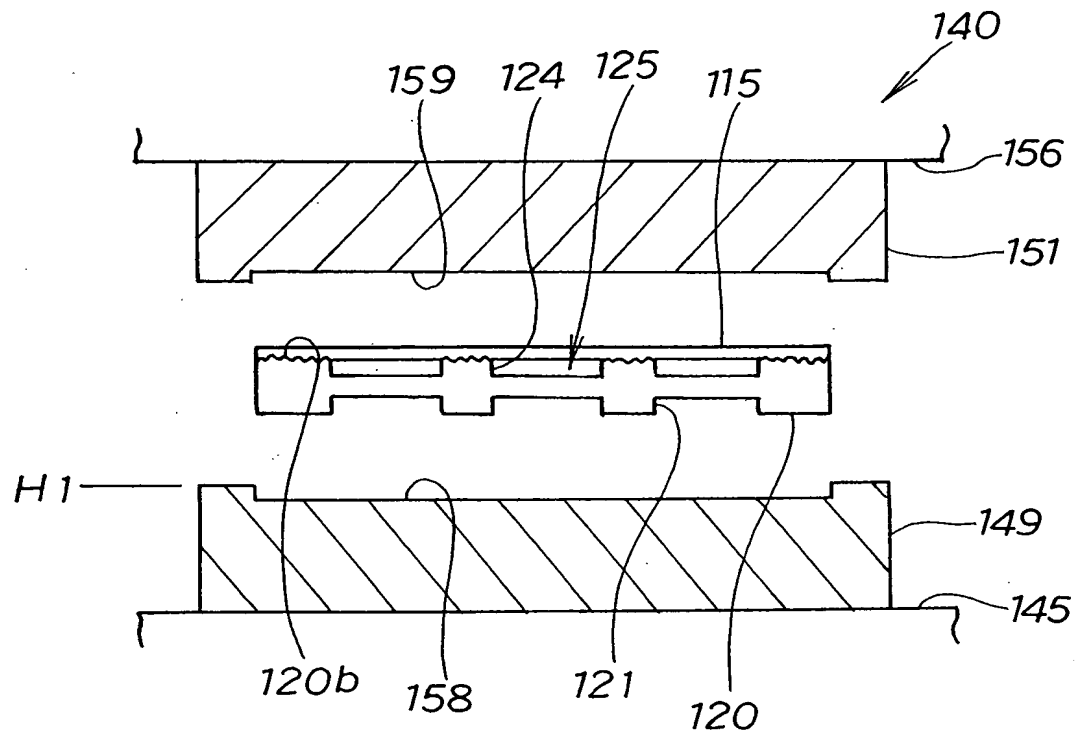


FIG. 15



This diagram shows a cross-sectional view of a second embodiment of the device. It features a top substrate 140 and a bottom substrate 145, both indicated by dashed lines. A central layer 130 is positioned between them. This layer 130 contains a series of rectangular openings 137. Above the layer 130, there is a layer 156 with a wavy surface 151. A horizontal double-headed arrow with a small circle in the center is located between the top substrate 140 and the wavy surface 151. Below the layer 130, there is a layer 149. A vertical upward-pointing arrow labeled F2 is shown between the bottom substrate 145 and the layer 149. Various other labels are present: 130b and 159 point to the top surface of the layer 130; 116 points to the top surface of the top substrate 140; 130a, 138, and 137 point to the bottom surface of the layer 130; 158 points to the bottom surface of the layer 149; and H3 is a label on the left side of the diagram.

FIG. 1 9A

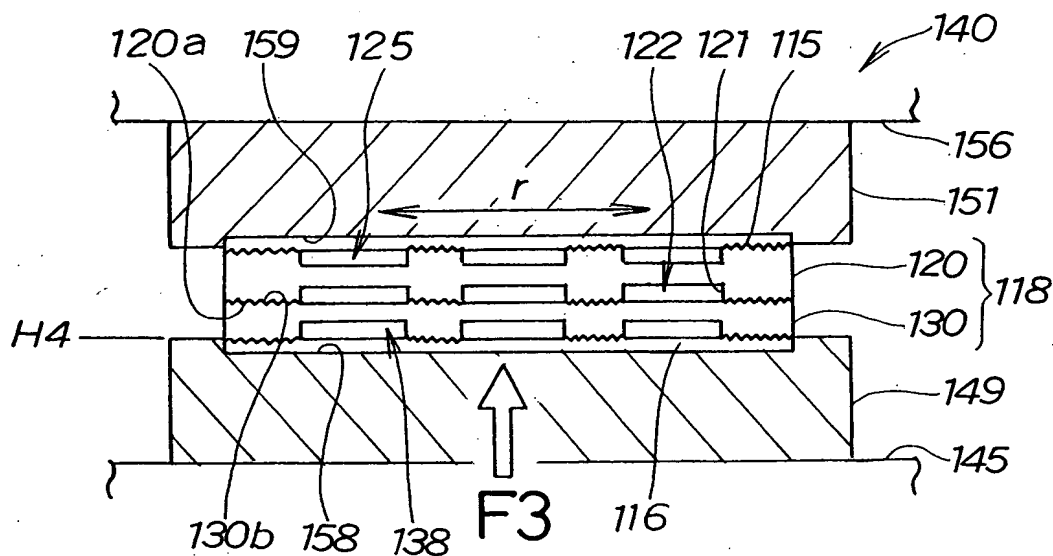


FIG. 1 9B

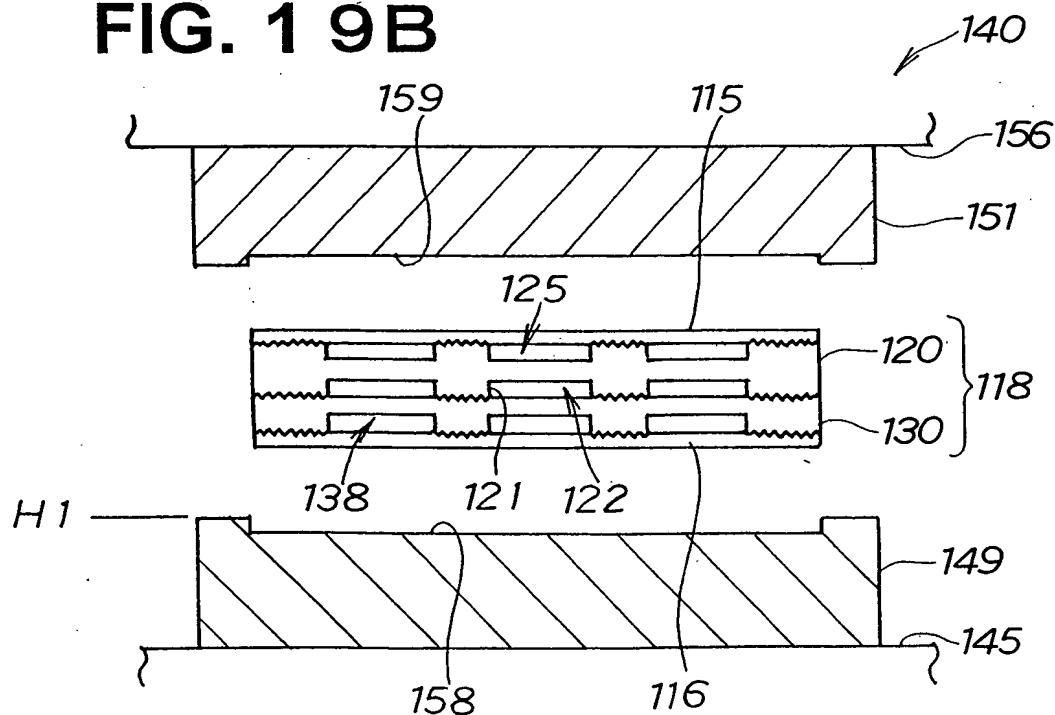


FIG. 20

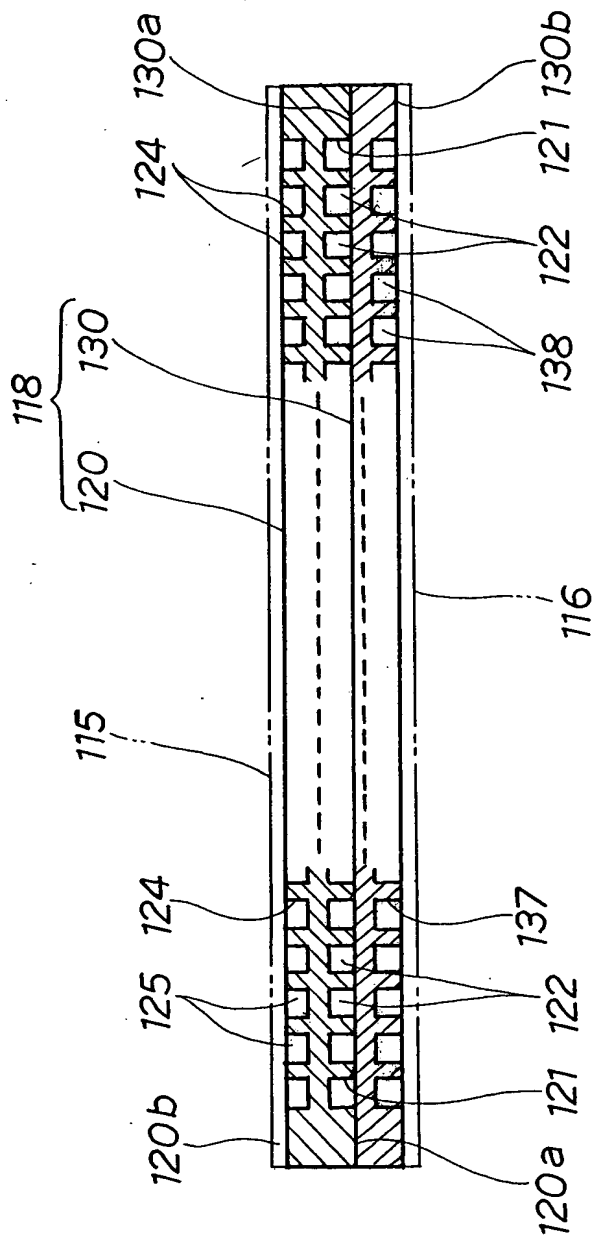


FIG. 22A

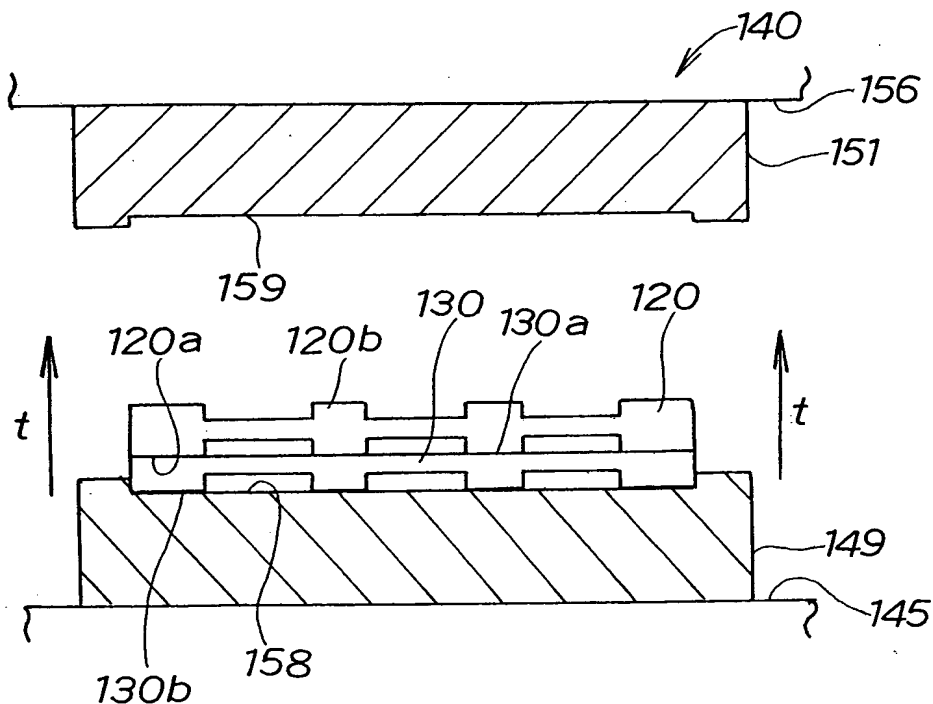
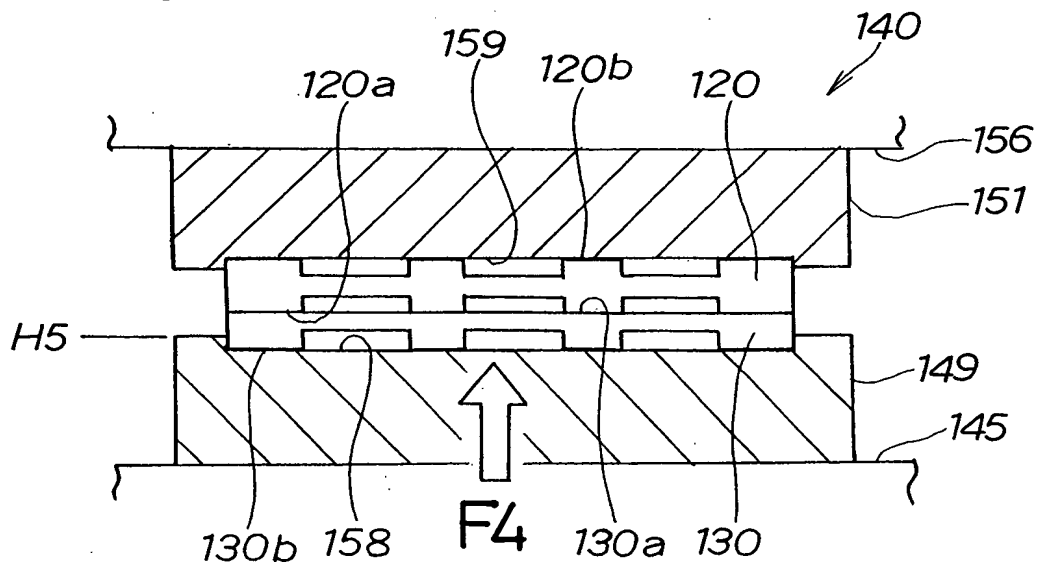


FIG. 22B



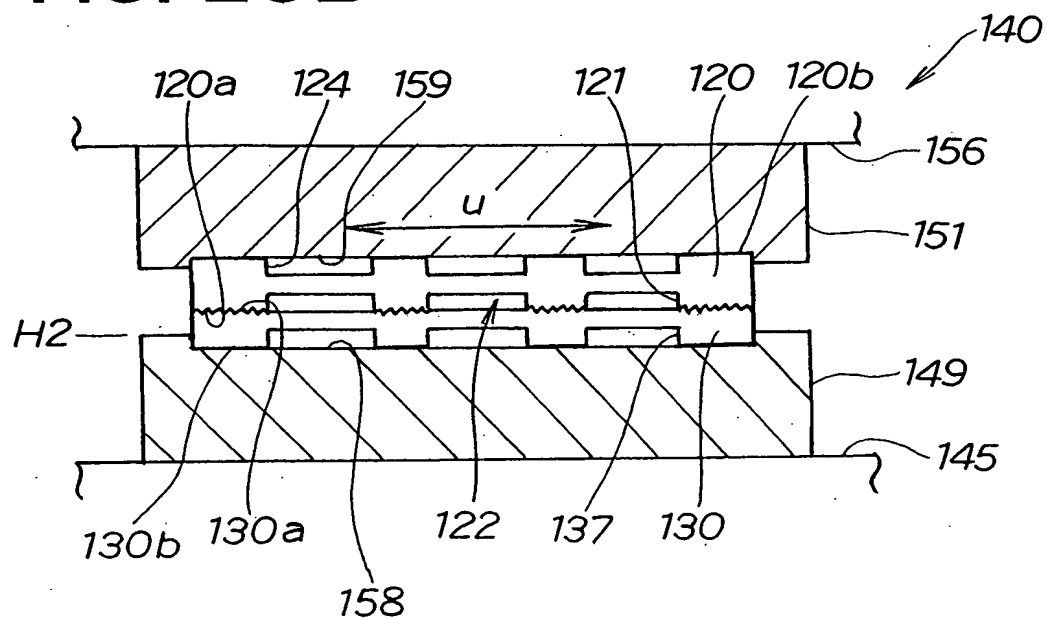
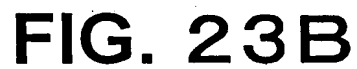
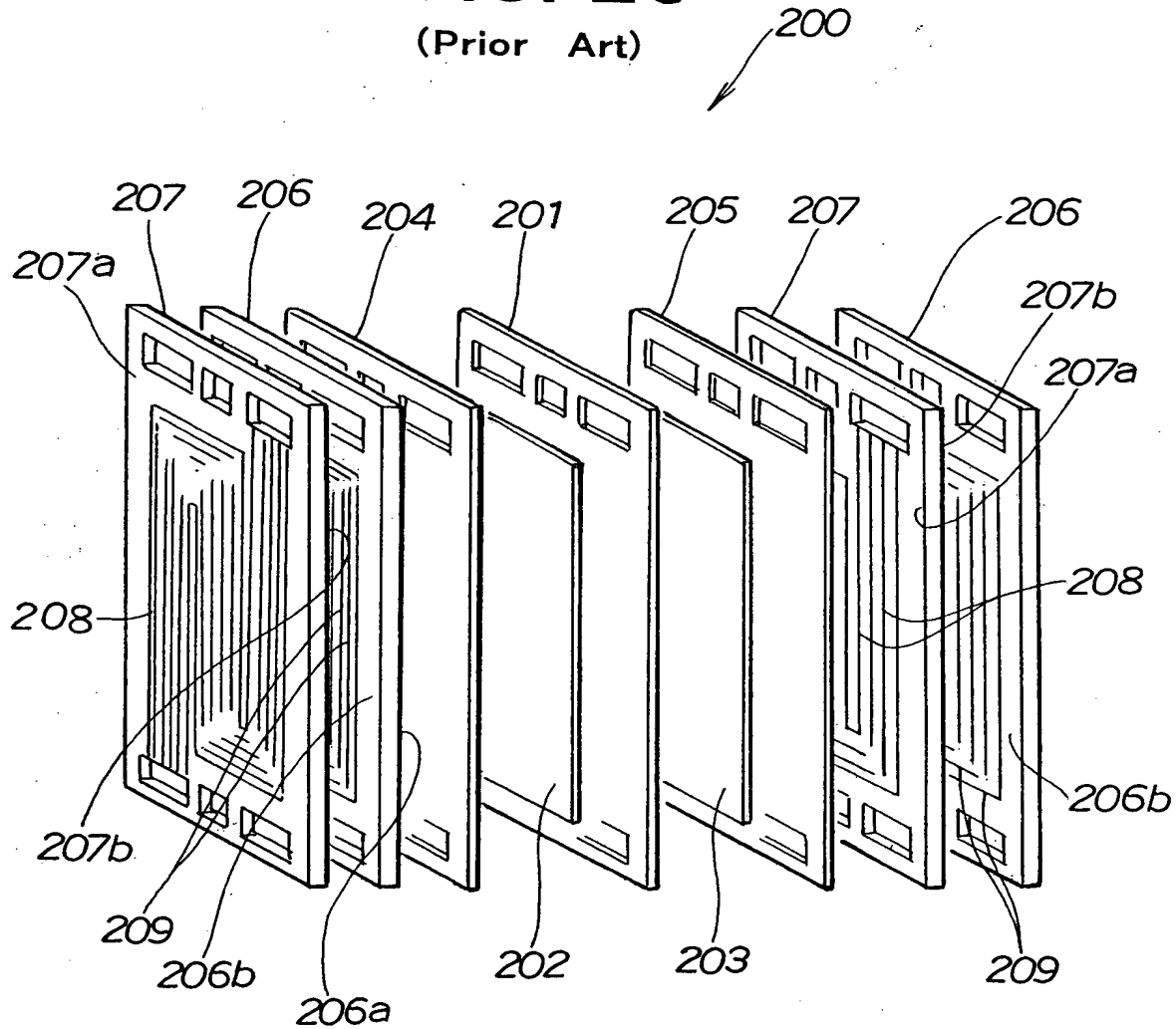


FIG. 25

(Prior Art)



300 

